

# Revision history of Board Changes

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## Note

*The xWR6843ISK Rev.C is an 8-layer board mainly due to the addition of the 60-Pin Samtec connector added for direct DCA100EVM connector and the layout requirements for high speed LVDS traces routed to the connector. Rev B is still a valid reference for 6-layer board design*

Board Revision	Details of changes	Device version
IWR6843ISK Rev A	Baseline document	ES1.0
IWR6843ISK Rev B	Module board could be plugged in both the orientation; ECO rolled in to design to fix this	ES1.0 and ES2.0 (Pre-production silicon)
IWR6843ISK Rev C	<ol style="list-style-type: none"><li>1. 2 CAN interface added onboard</li><li>2. USB added for data and power</li><li>3. 60 Pin Samtec connector added for direct DCA100EVM connector</li><li>4. Switch added for multiplexing SPI &amp; UART,</li><li>5. SOP switches and buttons also added</li><li>6. CP2105 USB to UART added</li><li>7. PMIC changed to LP87524 to support 5V input</li></ol>	ES2.0 (RTM silicon)
IWR6843ISK Rev D	<ol style="list-style-type: none"><li>1. Additional capacitors added to improve power integrity</li><li>2. Change in EVM form factor</li></ol>	ES2.0 (RTM silicon)

Board Revision	Details of changes	Device version
MMWAVICBOOST Rev B	<ol style="list-style-type: none"> <li>1. Module board could be plugged in both the orientation: ECO rolled in to design</li> <li>2. SOP lines are not getting registered sometimes (Increased the reset time constant)</li> <li>3. Make DNI for 12V path, Trace, DMM, Debug header and MiPI 60 pin connector (Most use case scenario)</li> <li>4. SOP0 and SOP2 Silk text interchanged: Incorporated in the design</li> </ol>	N/A